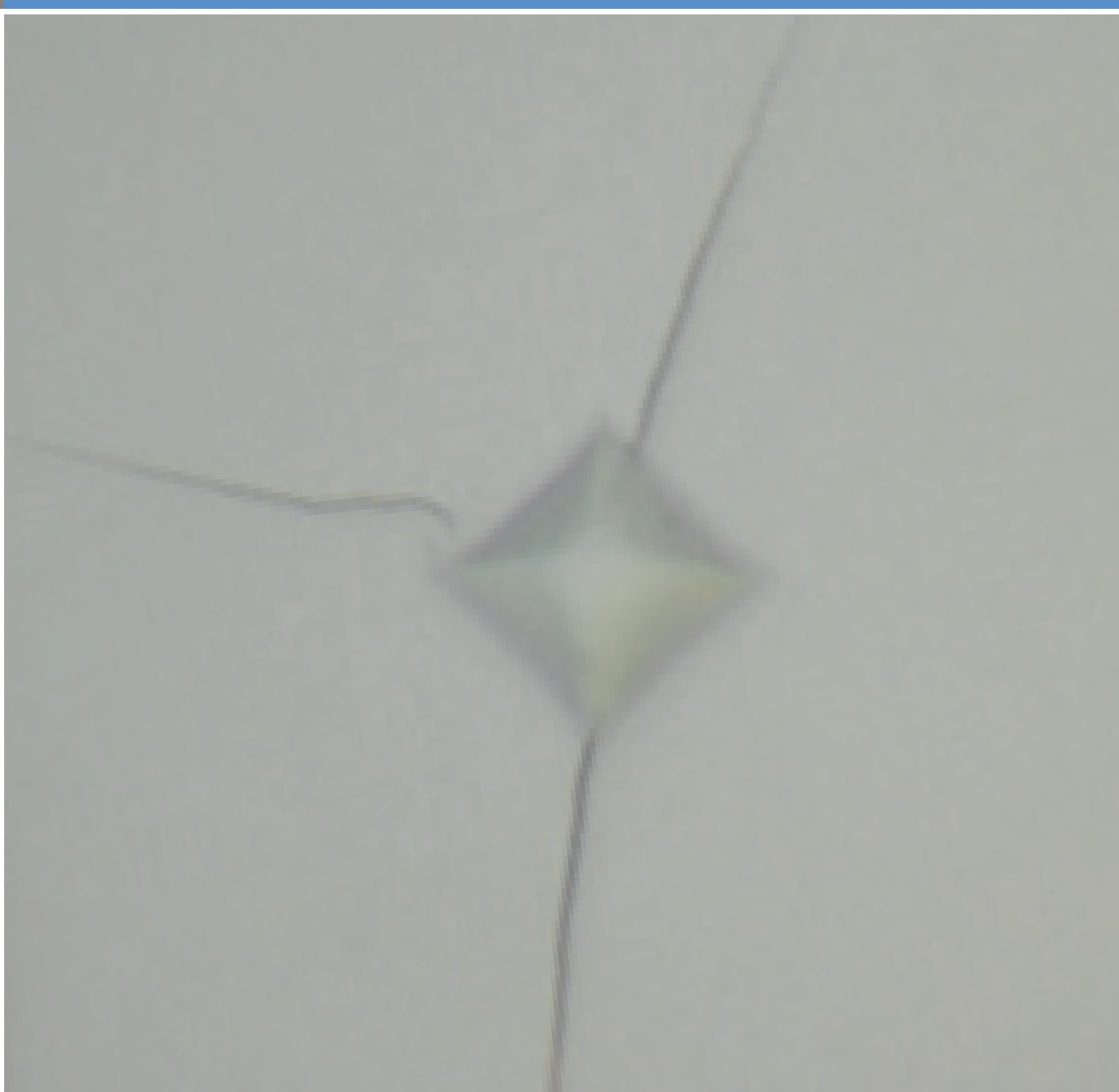
Xenolyte® Ni TR

mks Atotech

High temperature resistant Ni for RDL and pad metallization

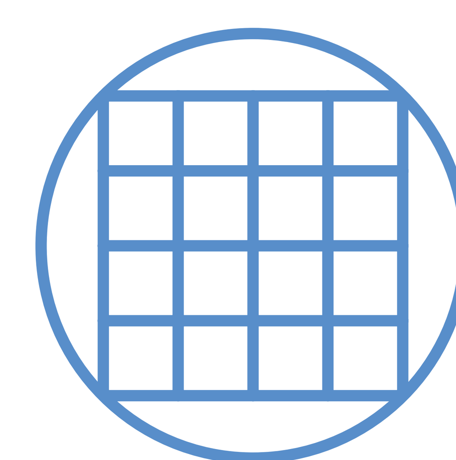
Fracture toughness (indenter test after 10 min at 400 °C)

Deposits from standard binary Ni systems show a tendency for cracking after treatment	Deposits from Xenolyte® Ni TR show no crack formation after thermal treatment
	

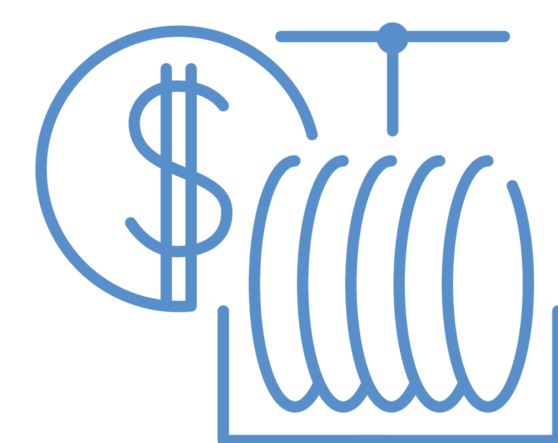
up to

450 °C

treatment possible without any cracks



Reduced stress for Taiko wafer processing



Capable for batch processing in wet bench

Stable process for automotive and power IC customers

Our electroless Xenolyte® Ni TR process is part of the ENEPIG/ENIG RDL and pad metallization portfolio and perfectly addresses the requirements of growing automotive and power industry. The nickel deposits from Xenolte® Ni TR withstand even high temperature budgets of up to 450 °C during chip processing.

Features and benefits

- Nickel alloy with molybdenum and low phosphorous (1.5 - 4%) deposition
- Effective diffusion/migration barrier
- Lower resistivity compared to binary systems
- Suitable for high temperature soldering > 400 °C
- Low stress post deposition and at higher temperature
- High hardness and fracture toughness
- Long bath life up to 2 MTO
- RoHS compatible